



## Material Content Data Sheet



<b>Sales Product Name</b>		BTS50025-1TAD		<b>Issued</b>		16. July 2019		
<b>MA#</b>		MA004091366						
<b>Package</b>		PG-TO263-7-10		<b>Weight*</b>		1556.46 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip_1	inorganic material	silicon	7440-21-3	6.524	0.42	0.42	4191	4191
chip_2	inorganic material	silicon	7440-21-3	1.848	0.12	0.12	1187	1187
leadframe	inorganic material	phosphorus	7723-14-0	0.247	0.02		159	
	non noble metal	iron	7439-89-6	0.823	0.05		529	
	non noble metal	copper	7440-50-8	822.375	52.83	52.90	528362	529050
	non noble metal	aluminium	7429-90-5	11.981	0.77	0.77	7697	7697
wire	organic material	carbon black	1333-86-4	8.429	0.54		5416	
	plastics	epoxy resin	-	92.723	5.96		59573	
encapsulation	inorganic material	silicondioxide	60676-86-0	460.806	29.61	36.11	296060	361049
	non noble metal	tin	7440-31-5	12.163	0.78	0.78	7814	7814
plating	inorganic material	phosphorus	7723-14-0	0.007	0.00		5	
	non noble metal	nickel	7440-02-0	2.941	0.19	0.19	1889	1894
solder	non noble metal	tin	7440-31-5	0.093	0.01		60	
	noble metal	silver	7440-22-4	0.116	0.01		75	
	non noble metal	lead	7439-92-1	4.430	0.28	0.30	2846	2981
	plastics	Polyimide	26023-21-2	0.198	0.01	0.01	127	127
glue	inorganic material	phosphorus	7723-14-0	0.039	0.00		25	
heatspreader	non noble metal	iron	7439-89-6	0.131	0.01		84	
	non noble metal	copper	7440-50-8	130.589	8.39	8.40	83901	84010
*deviation	< 10%				Sum in total:	100.00		1000000

### Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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